

1. General description

Hyperfast power diode in a SOD59 (2-lead TO-220AC) plastic package.

2. Features and benefits

- · Low reverse recovery current and low thermal resistance
- Reduces switching losses in associated MOSFET

3. Applications

- Continuous Current Mode (CCM) Power Factor Correction (PFC)
- Half-bridge/full-bridge switched-mode power supplies
- Half-bridge lighting ballasts

4. Quick reference data

| Table 1. Qui | ck reference data | | | | | |
|--------------------|---------------------------------|---|-----|-----|------|------|
| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
| V _{RRM} | repetitive peak reverse voltage | | - | - | 600 | V |
| I _{F(AV)} | average forward current | $\delta = 0.5$; T _{mb} \leq 109 °C; square-wave pulse; Fig. 1; Fig. 2 | - | - | 8 | A |
| Static chara | acteristics | | | | | |
| V _F | forward voltage | I _F = 8 A; T _j = 150 °C; <u>Fig. 4</u> | - | 1.4 | 1.85 | V |
| Dynamic ch | aracteristics | | | | | |
| t _{rr} | reverse recovery time | $ I_F = 8 \text{ A}; V_R = 400 \text{ V}; \text{d} \text{I}_F/\text{d} \text{t} = 500 \text{ A}/\mu\text{s}; \\ \text{T}_j = 25 ^\circ\text{C}; \underline{\text{Fig. 5}} $ | - | 19 | - | ns |

5. Pinning information

| Table 2. | Pinning in | formation | | |
|----------|------------|------------------------|---|----------------|
| Pin | Symbol | Description | Simplified outline | Graphic symbol |
| 1 | К | cathode | mb | K – K – A |
| 2 | А | anode | | 001aaa020 |
| mb | mb | mounting base; cathode | C C C C C C C C C C C C C C C C C C C | |

6. Ordering information

Table 3. Ordering information

| Type number | Package | | | | |
|-------------|----------|--|---------|--|--|
| | Name | Description | Version | | |
| BYC8-600 | TO-220AC | plastic single-ended package; heatsink mounted; 1 mounting hole; 2-lead TO-220AC | SOD59 | | |

BYC8-600

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Мах | Unit |
|--------------------|---------------------------------|--|-----|-----|------|
| V _{RRM} | repetitive peak reverse voltage | | - | 600 | V |
| V _{RWM} | crest working reverse voltage | | - | 600 | V |
| I _{F(AV)} | average forward current | δ = 0.5; T _{mb} ≤ 109 °C; square-wave pulse; Fig. 1; Fig. 2 | - | 8 | A |
| I _{FRM} | repetitive peak forward current | δ = 0.5 ; t _p = 25 µs; T _{mb} ≤ 109 °C; square-wave pulse | - | 16 | A |
| I _{FSM} | non-repetitive peak | t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse | - | 80 | А |
| | forward current | t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse | - | 88 | A |
| T _{stg} | storage temperature | | -40 | 150 | °C |
| Tj | junction temperature | | - | 150 | °C |

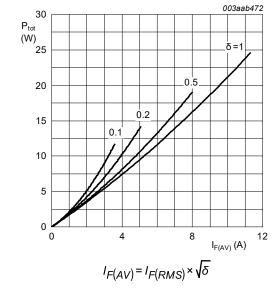


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

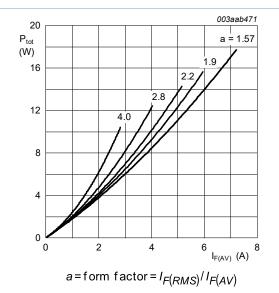


Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

Hyperfast power diode

8. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|-----------------------|--|---------------|-----|-----|-----|------|
| R _{th(j-mb)} | thermal resistance from junction to mounting base | <u>Fig. 3</u> | - | - | 2.2 | K/W |
| R _{th(j-a)} | thermal resistance from junction to ambient free air | | - | 60 | - | K/W |

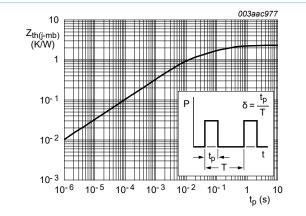
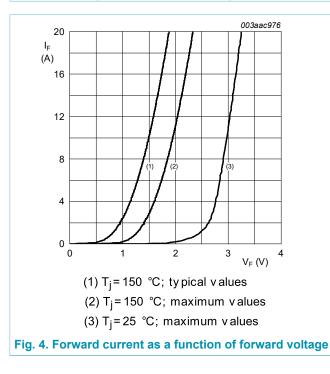


Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width

Hyperfast power diode

9. Characteristics

| Symbol | Parameter | Conditions | Min | Тур | Max | Unit |
|-----------------|----------------------------------|---|-----|-----|------|------|
| Static chara | acteristics | | | | | |
| V _F | forward voltage | I _F = 8 A; T _j = 25 °C | - | 2 | 2.9 | V |
| | | I _F = 8 A; T _j = 150 °C; <u>Fig. 4</u> | - | 1.4 | 1.85 | V |
| | | I _F = 16 A; T _j = 150 °C | - | 1.7 | 2.3 | V |
| I _R | reverse current | V _R = 600 V; T _j = 25 °C | - | 9 | 150 | μA |
| | | V _R = 600 V; T _j = 100 °C | - | 1.1 | 3 | mA |
| Dynamic ch | naracteristics | | | | | |
| t _{rr} | reverse recovery time | $I_F = 1 \text{ A}; V_R = 30 \text{ V}; dI_F/dt = 50 A/\mu \text{s}; \\ T_j = 25 ^\circ\text{C}; \underline{Fig. 5}$ | - | 30 | 52 | ns |
| | | $ I_F = 8 \text{ A}; \text{ V}_R = 400 \text{ V}; \text{ d}I_F/\text{d}t = 500 \text{ A}/\mu\text{s}; \\ T_j = 25 \text{ °C}; \text{ Fig. 5} $ | - | 19 | - | ns |
| | | $ I_F = 8 \text{ A}; \text{ V}_R = 400 \text{ V}; \text{ d}I_F/\text{d}t = 500 \text{ A}/\mu\text{s}; \\ T_j = 100 ^\circ\text{C}; \text{ Fig. 5} $ | - | 32 | 40 | ns |
| I _{RM} | peak reverse recovery current | I_{F} = 8 A; V_{R} = 400 V; dI_{F}/dt = 50 A/µs; T_{j} = 125 °C | - | 1.5 | 5.5 | A |
| | | I_{F} = 8 A; V_{R} = 400 V; dI_{\text{F}}/dt = 500 A/µs; T_{j} = 100 °C | - | 9.5 | 12 | A |
| Q _r | recovered charge | I_{F} = 1 A; V_{R} = 100 V; dI_{F}/dt = 100 A/µs; T_{j} = 25 °C | - | 12 | - | nC |
| V _{FR} | forward recovery voltage | I _F = 10 A; dI _F /dt = 100 A/µs; T _j = 25 °C; <u>Fig. 6</u> | - | 8 | 10 | V |



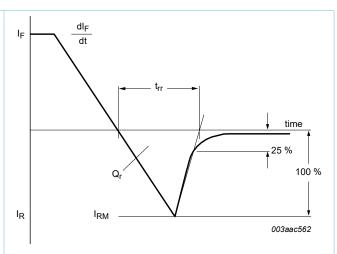
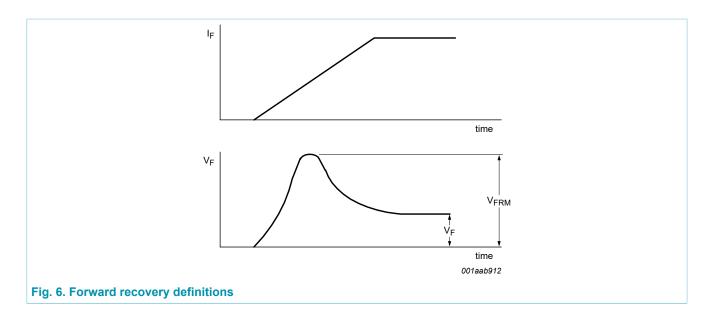


Fig. 5. Reverse recovery definitions; ramp recovery

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BYC8-600

Hyperfast power diode



BYC8-600

Hyperfast power diode

10. Package outline

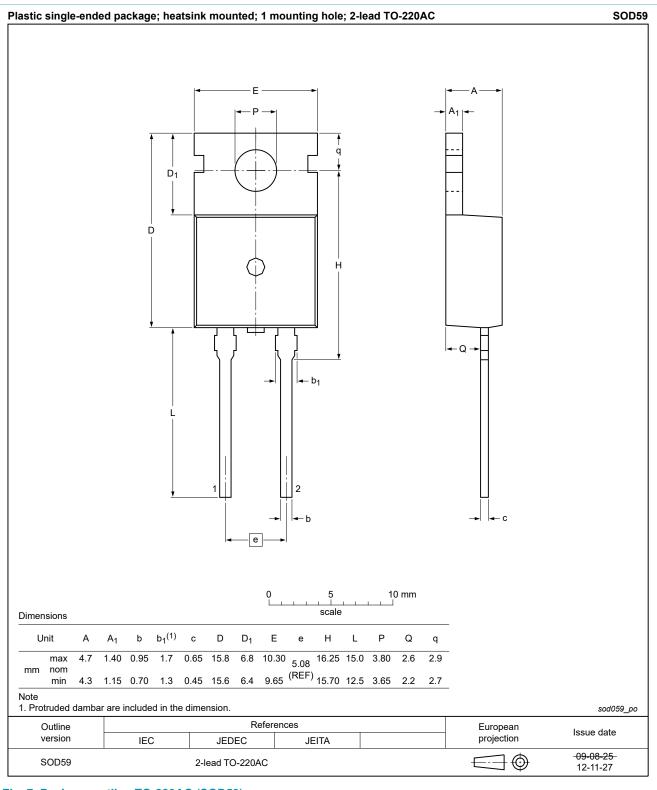


Fig. 7. Package outline TO-220AC (SOD59)

BYC8-600

Hyperfast power diode

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| Document status [1][2] | Product status [<u>3]</u> | Definition |
|--------------------------------------|-------------------------------|---|
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